

adhesion between a wafer and a photoresist layer when the photoresist layer is deposited onto the wafer and that generates a process deteriorating gas; and

*Call
out* a bake unit installed in the production line, the bake unit being adapted to bake the wafer having the photoresist layer formed thereon, the baking being susceptible to operational failures if exposed to the process deteriorating gas,

wherein the bake unit is installed at a higher level than the adhesion unit, and

wherein clean air flows downward over the adhesion and bake units to carry the process deteriorating gas away from the bake unit.

Please cancel claim 2 without prejudice or disclaimer..

REMARKS

Applicants gratefully acknowledge that the Examiner has allowed claims 8-12.

Reexamination and reconsideration of the present application are requested.

Applicants have amended claim 1 and canceled claim 2. Accordingly, claims 1 and 3-12 remain pending in the application.

DRAWINGS

The Examiner objected to the drawings as allegedly failing to show certain features of the claims. Namely, the Office Action stated that the following features are not shown in the drawings: (1) “a first semiconductor process unit installed higher than a second semiconductor processing unit;” (2) “a first semiconductor